

Abstract

Leading wires of an electrical circuit and a thin film magnetic head assembly are electrically connected with a conductive film. The leading wires are connected to an element pad and a circuit pad, respectively. An element bump is shared with the electrical circuit and the thin film magnetic assembly. Information of the processing degree of the thin film magnetic head assembly is electrically monitored via the element bump from a bonding pad which is electrically connected with the element bump.

1007653-021902